

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4205426

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHAO-JEN WANG	12/28/2016
CHIH-CHIA CHANG	12/28/2016
JIA-CHONG HO	12/28/2016
RECEIVING PARTY DATA	
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Property Type	Number
Application Number:	15394814
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SIGNATURE:	/Belinda Lee/
DATE SIGNED:	12/30/2016
Total Attachments: 2	
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ASSIGNMENT

WHEREAS,

1. Chao-Jen Wang
2. Chih-Chia Chang
3. Jia-Chong Ho

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **CHIP PACKAGE AND CHIP PACKAGING METHOD**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS 1. Industrial Technology Research Institute
of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R.
O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Chao-Jen Wang
Sole or First Joint Inventor: Chao-Jen Wang

Date: 2016/12/28

Signature: Chih-chia chang
Second Joint Inventor (if any): Chih-Chia Chang

Date: 2016/12/28

Signature: Jou Choy Uee
Third Joint Inventor (if any): Jia-Chong Ho

Date: 2016/12/28